

Specification of Electret Condenser Microphone

(RoHS Compliance&Halogen-Free)

Customer Name :
Customer Model:
GoerTek Model : B4013AM423-008

Goer Tek	CUSTOMER APPROVAL
<u>DESIGN</u> <u>Archie.Kong/Apr.12,2013</u>	
<u>CHKD</u> <u>Dave.Zhao/Apr.12,2013</u>	
<u>STANDARD</u> <u>Lina.Zhao/Apr.12,2013</u>	
<u>APVD</u> <u>Worden.Wang/Apr.12,2013</u>	



Tel : + 86 536 8525015
Fax : + 86 536 8525000
E- Mail : goertek@goertek.com
Website: <http://www.goertekacoustics.com>
Address: No.268 Dongfang Road, High-Tech Industry
Development District, Weifang, Shandong, P.R.C.

Restricted

1 Security warning

The information contained in this document is the exclusive property of GoerTek Inc. and should not be disclosed to any third party without the written consent of GoerTek Inc.

2 Publication history

Version	Modified P/O No.	Date	Description	Design	Approval
1.0	/	2013.04.12	New Design	Archie	Worden

3 Symbols Show

Symbols	Show
©	Signify Customer's Special Characteristic.
©	Signify GoerTek Special Characteristic.

Contents

1	Test Condition	4
2	Electrical Characteristics	4
3	Frequency Response Curve and Limits	4
4	Measurement Circuit	5
5	Test Setup Drawing	5
6	Mechanical Characteristics	6
6.1	Appearance Drawing	6
6.2	Weight	6
7	Reliability Test	7
7.1	Vibration Test	7
7.2	Drop Test	7
7.3	Temperature Test	7
7.4	Humidity Test	7
7.5	Temperature Cycle Test	7
7.6	Temperature Shock Test	7
7.7	ESD Shock Test	7
7.8	Reflow Test	7
8	Package	8
8.1	Taping Specification	8
8.2	Reel Dimension	9
8.3	The Content of Box(13" reel)	9
8.4	Packing Explain	10
9	Stock and Transportation	10
10	Land Pattern Recommendation	11
10.1	Soldering Surface - Land Pattern	11
10.2	Metal Mask Pattern	11
11	Recommend Soldering	12
11.1	Soldering Machine Condition	12
11.2	The Pattern of the Nozzle	12
11.3	Reflow Profile	13
12	Cautions when Using SMD MIC	14
12.1	X-ray Inspection	14
12.2	Board Wash Restrictions	14
12.3	Nozzle Restrictions	14
13	Output Inspection Standard	14

PRODUCT SPECIFICATIONS

Type: Electret Condenser Microphone

Number: B4013AM423-008

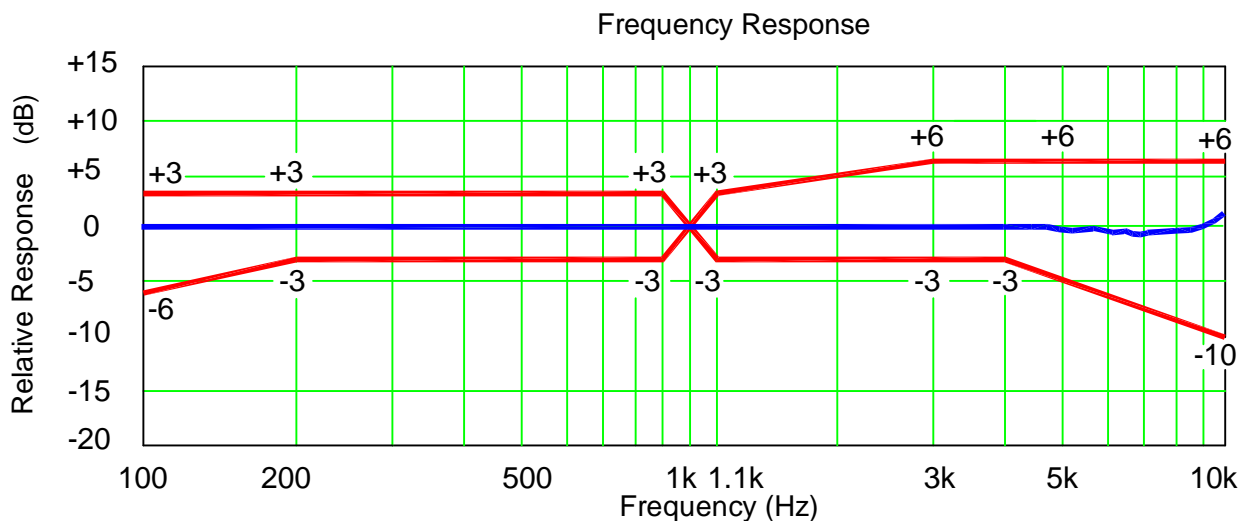
1 Test Condition ($V_s=2.0V$, $R_L=2.2k\Omega$, $L=50cm$)

Standard Conditions (As IEC 60268-4)	Temperature	Humidity	Air pressure
Environment Conditions	+15°C ~ +35°C	45% RH ~ 75% RH	86kPa ~ 106kPa
Basic Test Conditions	+20°C ± 2°C	60% RH ~ 70% RH	86kPa ~ 106kPa

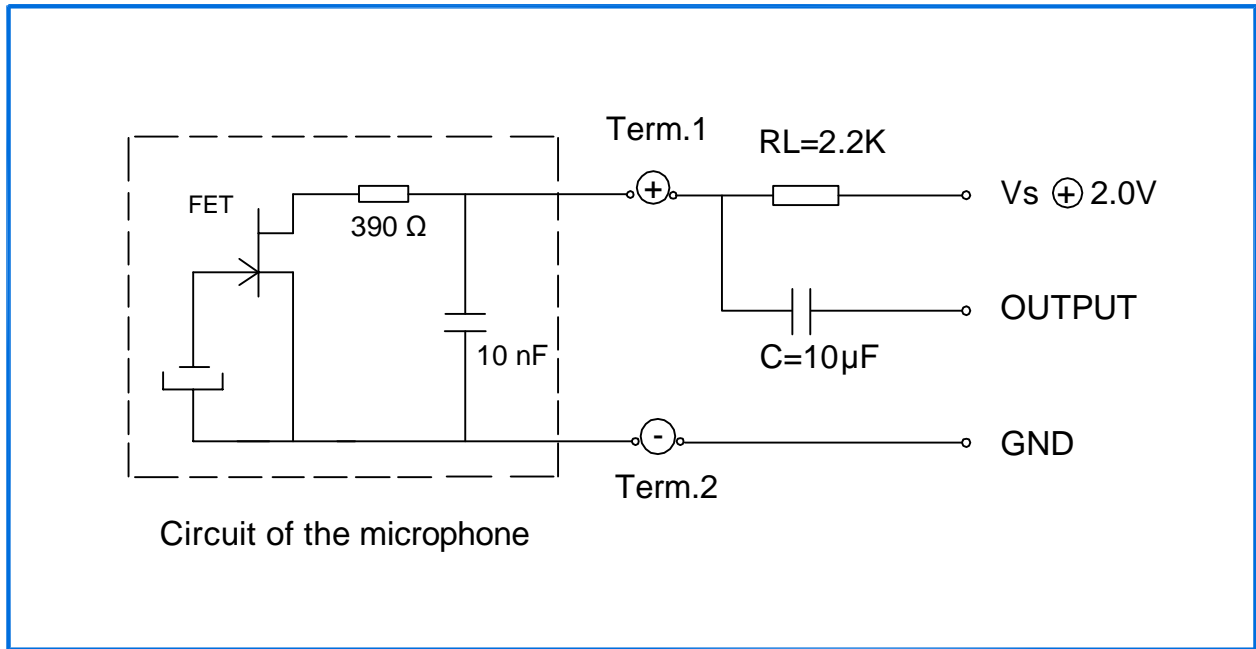
2 Electrical Characteristics

Item	Symbol	Test Conditions	Min	Standard	Max	Unit
Sensitivity	S	f=1kHz, Pin=1Pa	-45	-42	-39	dB 0dB=1V/Pa
Output Impedance	Zout	f=1kHz, Pin=1Pa			2.2k	Ω
Directivity	D(θ)	Omnidirectional				dB
Current Consumption	I				500	μA
S/N Ratio	S/N(A)	f=1kHz, Pin=1Pa A-Weighted Curve	60			dB
Decreasing Voltage Characteristic	ΔS	f=1kHz, Pin=1Pa $V_s=2.0-1.5V$			-3	dB
Operating Voltage Range	V_s		1.0		10	V
Distortion	THD	f=1kHz, Pin=104dB			3	%

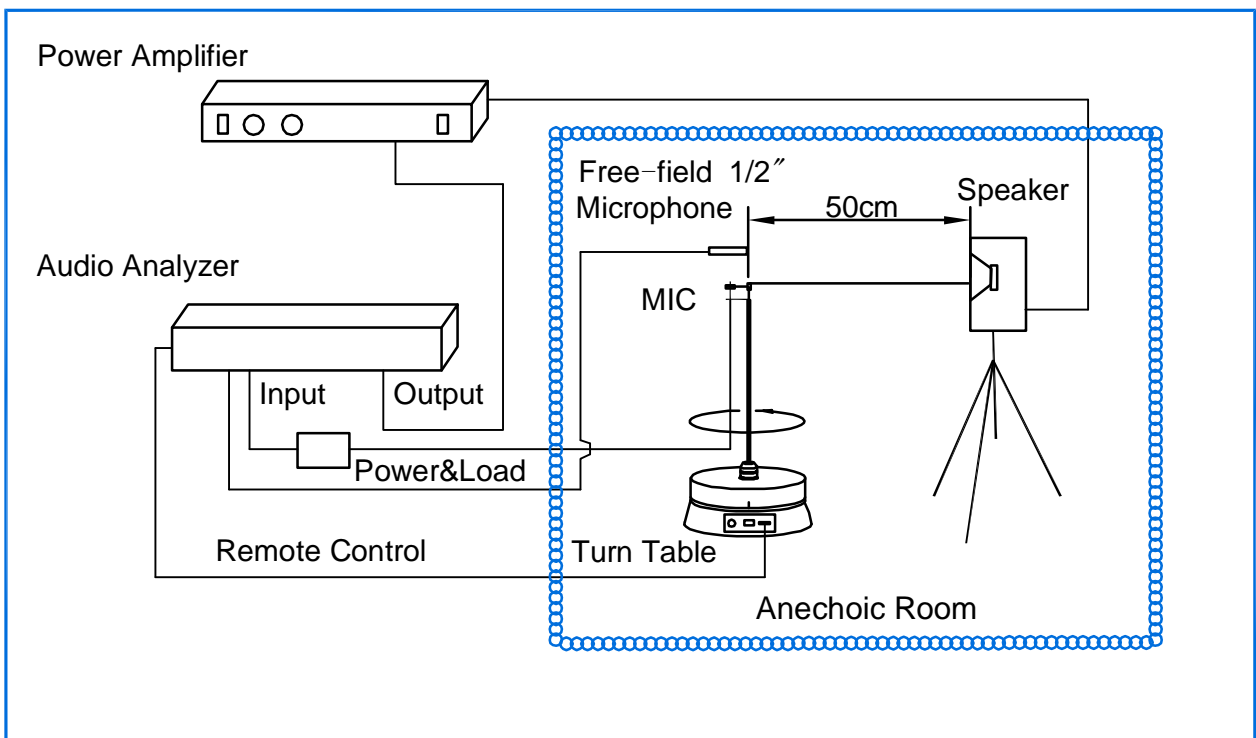
3 Frequency Response Curve and Limits



4 Measurement Circuit

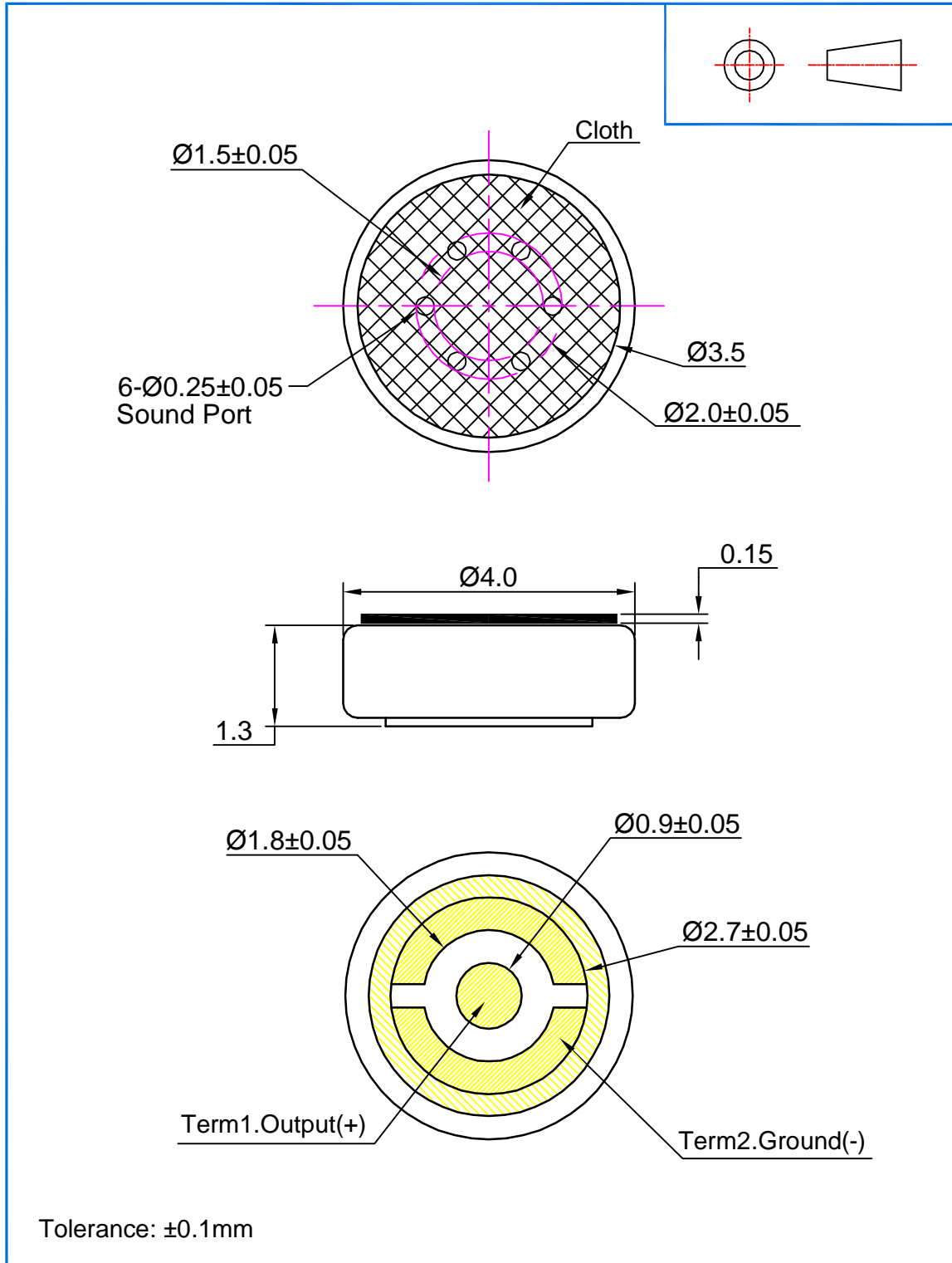


5 Test setup Drawing



6 Mechanical Characteristics

6.1 Appearance Drawing (Unit: mm)



6.2 Weight

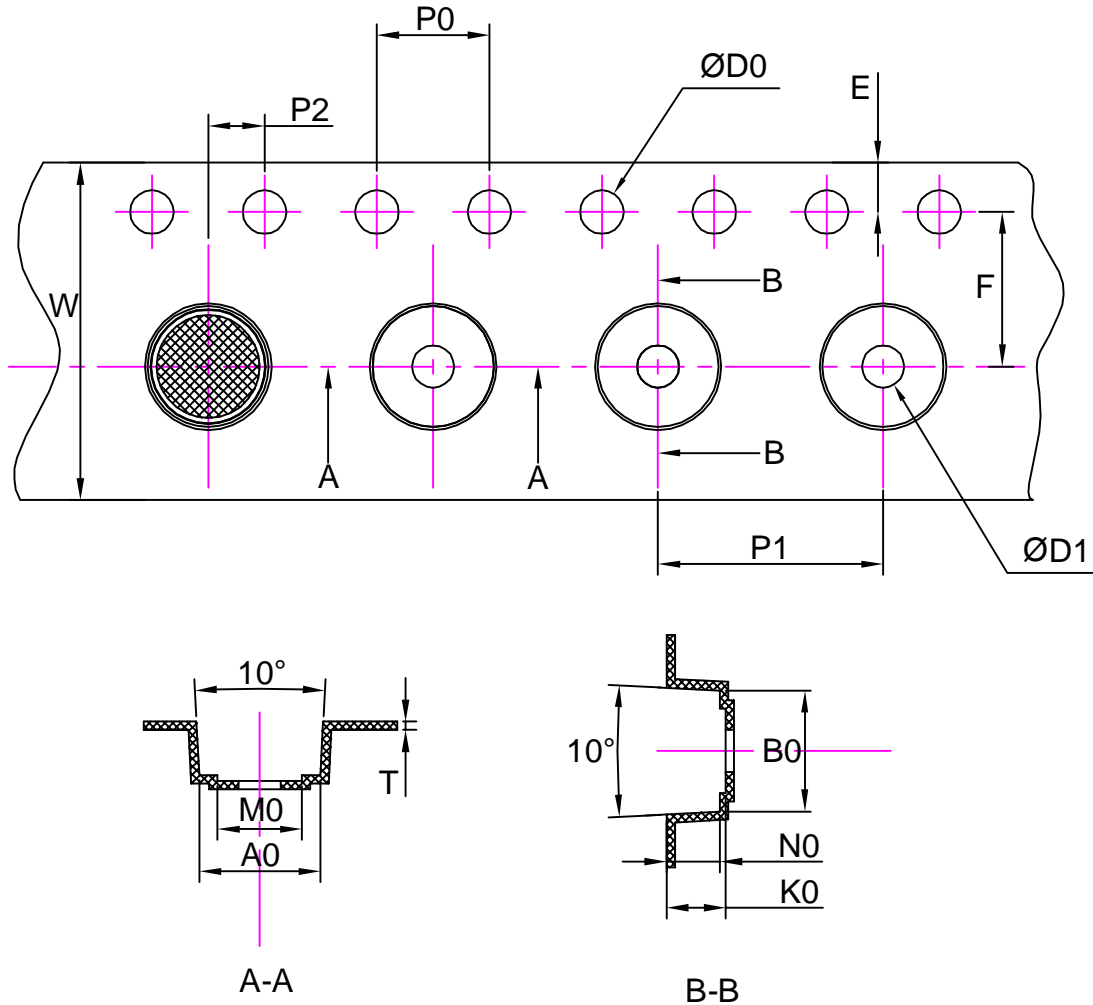
Less than 0.2g

7 Reliability Test

<p>7.1 Vibration Test</p>	<p>To be no interference in operation after vibrations,10Hz to 55 Hz for 1 minute full amplitude 1.52mm,for 2 hours at three axes in state of standard packing,sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C}\sim+35\text{ }^{\circ}\text{C}$, R.H 45%~75%)</p>
<p>7.2 Drop Test</p>	<p>To be no interference in operation after dropped to steel plate each one time from 1.5 meter height ,12 times,sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C}\sim+35\text{ }^{\circ}\text{C}$, R.H 45%~75%)</p>
<p>7.3 Temperature Test</p>	<p>a) After exposure at $+85^{\circ}\text{C}$ for 200 hours,sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C}\sim+35\text{ }^{\circ}\text{C}$, R.H 45%~75%) b) After exposure at -40°C for 200 hours,sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C}\sim+35\text{ }^{\circ}\text{C}$, R.H 45%~75%)</p>
<p>7.4 Humidity Test</p>	<p>After exposure at $+60^{\circ}\text{C}$ and 90~95% relative humidity for 200 hours,sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C}\sim+35\text{ }^{\circ}\text{C}$, R.H 45%~75%)</p>
<p>7.5 Temperature Cycle Test</p>	<p>After exposure at -40°C for 30 minutes, at 20°C for 10 minutes, at $+85^{\circ}\text{C}$ for 30 minutes, at 20°C for 10 minutes,5 cycles,sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C}\sim+35\text{ }^{\circ}\text{C}$, R.H 45%~75%)</p>
<p>7.6 Temperature Shock Test</p>	<p>After exposure at -40°C for 60 minutes, at $+85^{\circ}\text{C}$ for 60 minutes(change time 20 seconds), 32 cycles,sensitivity to be within $\pm 3\text{dB}$ from initial sensitivity. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C}\sim+35\text{ }^{\circ}\text{C}$, R.H 45%~75%)</p>
<p>7.7 ESD Shock Test</p>	<p>The microphone under test must be discharged between each ESD exposure without ground.(Contact:$\pm 8\text{kV}$;Air:$\pm 15\text{kV}$) There is no interference in operation after 10 times exposure.</p>
<p>7.8 Reflow Test</p>	<p>Adopt the reflow curve of item11.3,after two reflows,sensitivity to be within $-42\pm 3\text{dB}$. (The measurement to be done after 2 hours of conditioning at $+15\text{ }^{\circ}\text{C}\sim+35\text{ }^{\circ}\text{C}$, R.H 45%~75%)</p>

8 Package

8.1 Taping Specification



The dimensions as follows:

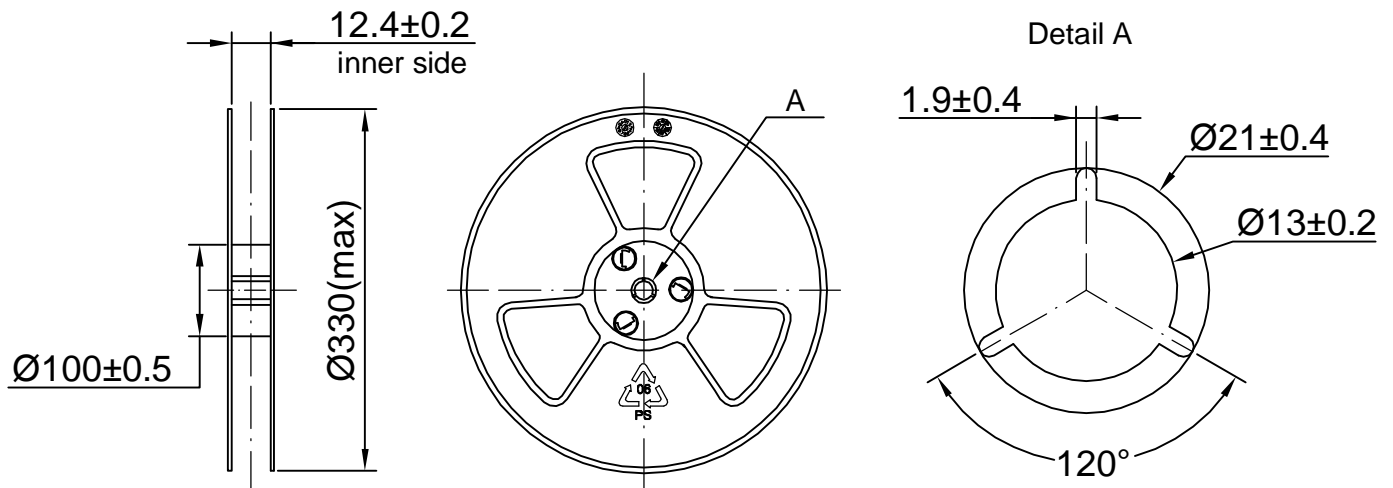
ITEM	W	E	F	ØD0	ØD1
DIM(mm)	12.0±0.30	1.75±0.10	5.50±0.05	1.50±0.10	1.55±0.10
ITEM	P0	10P0	P1	A0	B0
DIM(mm)	4.00±0.10	40.00±0.20	8.00±0.10	4.30±0.10	4.30±0.10
ITEM	K0	P2	T	M0	N0
DIM(mm)	1.70±0.10	2.00±0.05	0.35±0.05	3.30±0.05	1.50±0.05

8.2 Reel Dimension

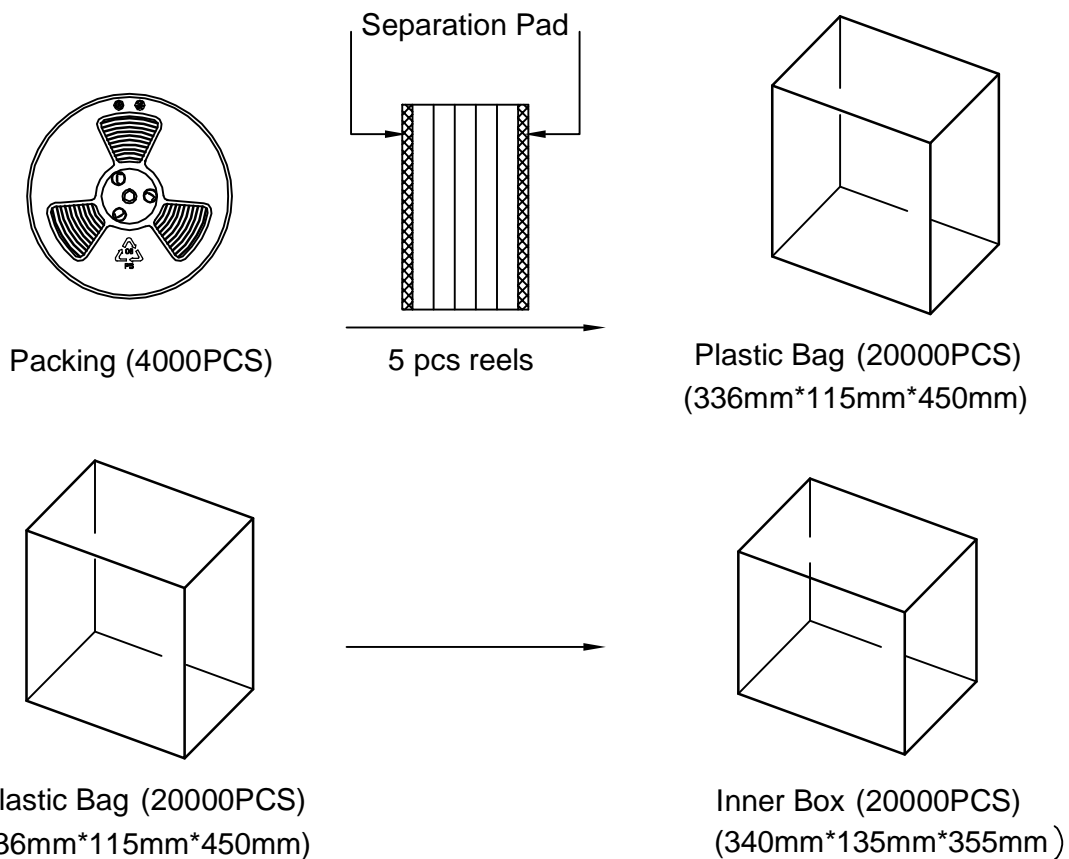
7 " reel for sample stage

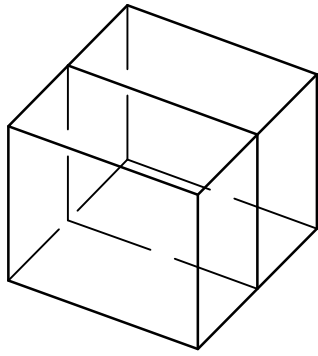
13 " reel will be provided for the mass production stage

The following is 13" reel dimensions (unit:mm)

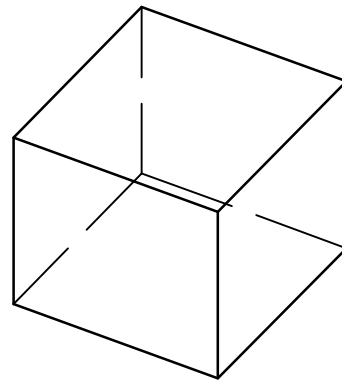
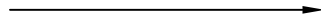


8.3 The content of box(13" reel)





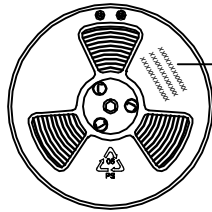
Two Inner Box(40000PCS)



Outer Box(40000PCS)
(370mm*300mm*390mm)

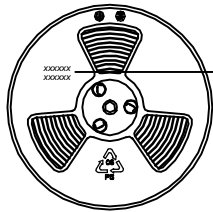
8.4 Packing Explain

8.4.1 The label content of the reel



The content including:
Product type, Lot, Customer P/N;
And other essential information such as
Quantity, Date etc.

8.4.2 The RoHS label



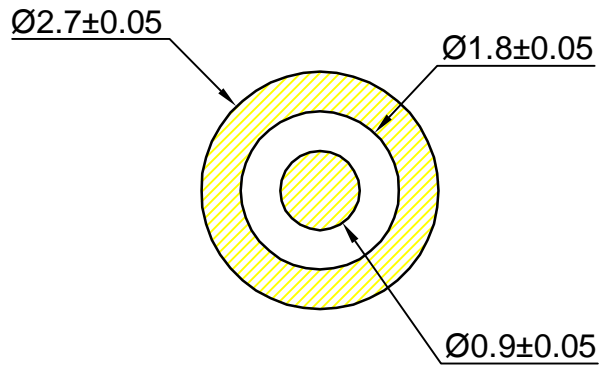
RoHS
compliance mark

9 Stock and Transportation

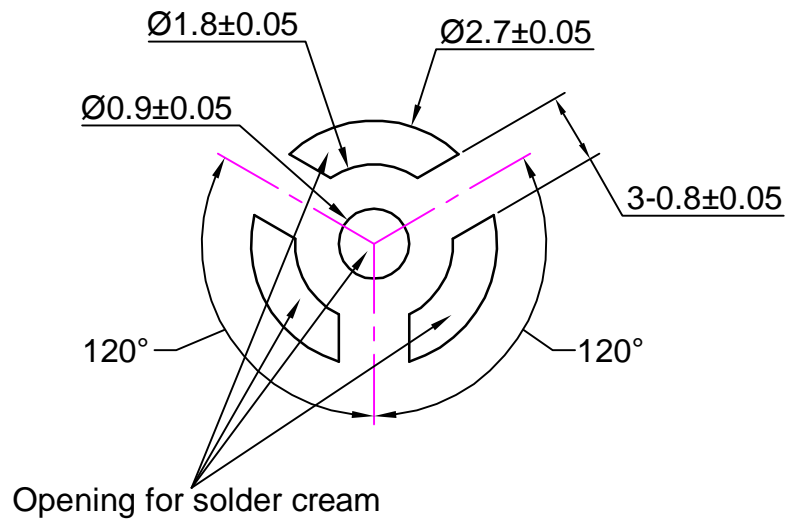
- 9.1 Keep ECM in warehouse with less than 75% humidity and without sudden temperature change, acid air, any other harmful air or strong magnetic field.
- 9.2 The ECM with normal pack can be transported by ordinary conveyances. Please protect products against moist, shock, sunburn and pressure during transportation.
- 9.3 Storage Temperature Range: -40 °C ~ +85 °C
- 9.4 Operating Temperature Range: -30 °C ~ +70 °C

10 Land Pattern Recommendation (Unit: mm)

10.1 Soldering Surface - Land Pattern



10.2 Metal Mask Pattern



- Thickness of metal mask: 0.1mm

11 Recommend Soldering

11.1 Soldering Machine Condition

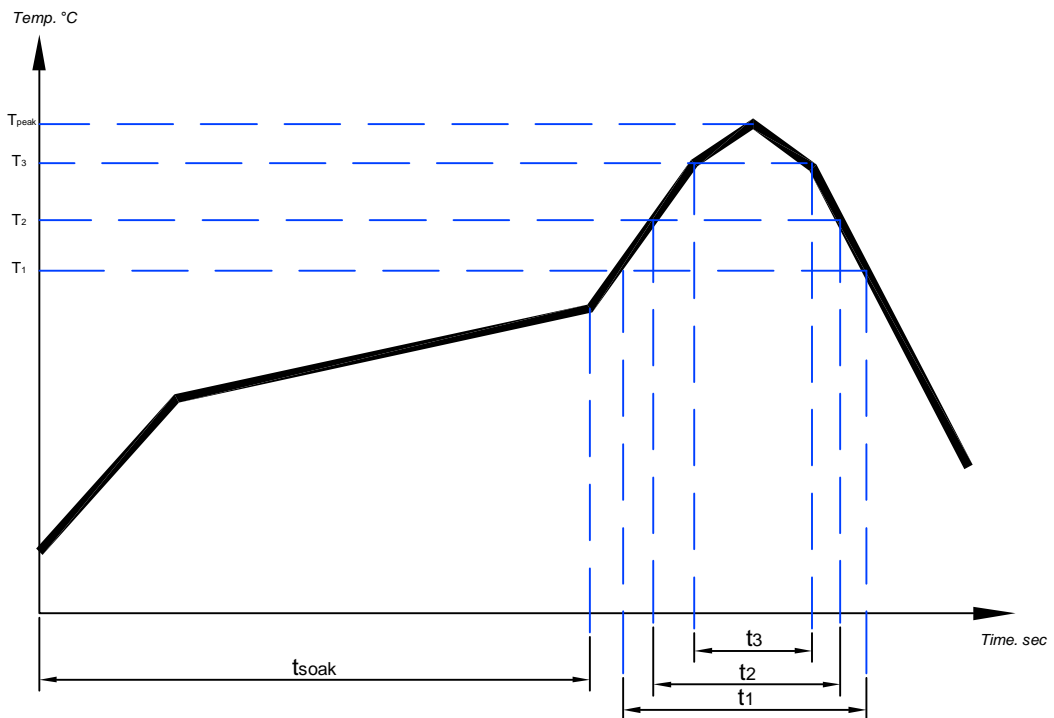
Temperature control	8 zones
Heater Type	Hot Air
Solder Type	Lead-free

11.2 The pattern of the nozzle



Dimension of nozzle: 504
External diameter: 1.5mm
Inside diameter: 1.0mm
Pick up position: bottom center of microphone

11.3 Reflow Profile



Pb-free reflow profile requirements for soldering heat resistance

Parameter	Reference	Specification
Average Temperature Gradient in Preheating	---	2.5°C/s
Soak Time	t_{soak}	2-3 Minutes
Time Above 217 °C	t_1	Max 60s
Time Above 230 °C	t_2	Max 50s
Time Above 250 °C	t_3	Max 10s
Peak Temperature In Reflow	T_{peak}	255°C (-0/+5°C)
Temperature Gradient In Cooling	---	Max -5°C/s

When SMD MIC is soldered on PCB, the reflow profile is set according to solder paste and the thickness of PCB etc.

12 Cautions when using SMD MIC

12.1 X-ray inspection

The microphone should not be subjected to X-ray inspection. If it is absolutely necessary to do inspection using X-ray, the setting conditions with the following conditions:

Distance: >0.08meter;

Current: <0.080mA;

Time: <30s;

Voltage: <80kV.

12.2 Board wash restrictions

It is very important not to wash the PCB after reflow process, or this could damage the microphone.

12.3 Nozzle restrictions

It is very important not to pull a nozzle over the post hole of the microphone. or this could damage the microphone.

13 Output Inspection standard

Output inspection standard is excuted according to <<ISO2859-1:1999>>.